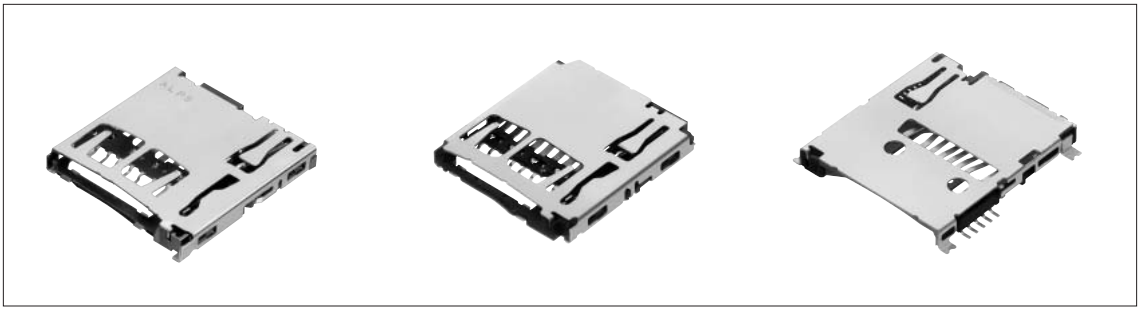
Connector for microSD™ Card (Push-push Ejection Type)

SCHA Series

Best for the mobile phone in the compact size and low-profile.



RoHS applicable

Features

- Clearly defined click.
- Achievement of good operation feeling.

Applications

- Mobile phones, personal digital assistants, digital still cameras, compact portable equipment, etc.

Typical Specifications

Items			Specifications
Structure	Applicable media		microSD™ Card
	Mounting method		Surface mounting type
	Mounting system		Standard mount/Reverse mount
	Media ejection structure		Push-push type
Performance	Operating temperature range		−20℃ to +70℃
	Voltage proof		500V AC 1 minute
	Insulation resistance (Initial)		1,000MΩ min.
	Contact resistance (Initial)	Connector contacts	100mΩ max.
		Detection switch	500mΩ max.
	Mating and unmating cycle		5,000 cycles

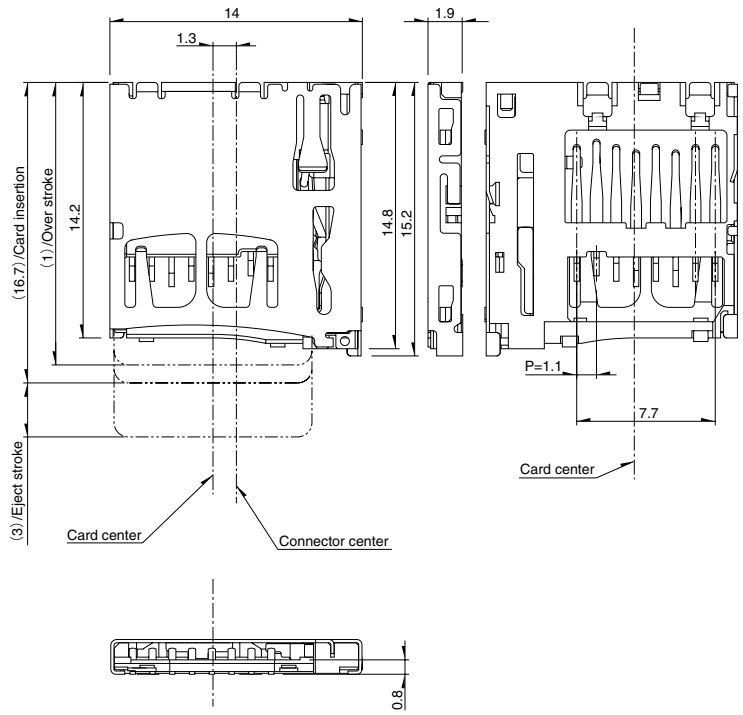
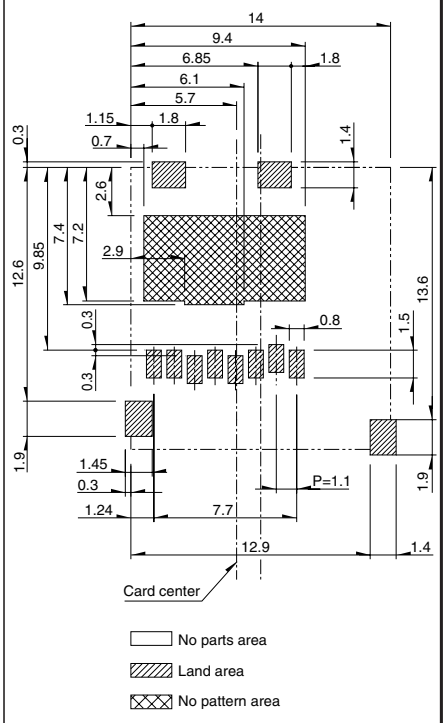
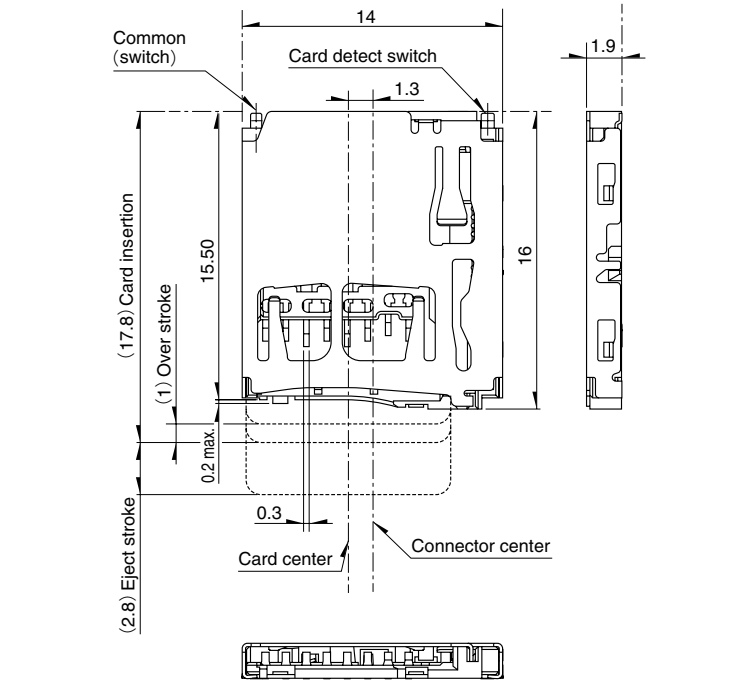
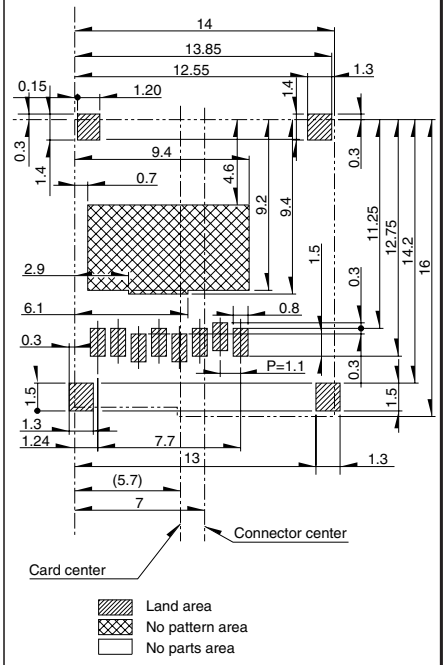
Products List

Media ejection structure	Mounting system	Features	Stand-off (mm)	Packing system	Product No.	Drawing No.
Push-push type	Standard mount	Without switch	0	Taping	SCHA1A0101	1
		With switch			SCHA1B0100	2
	Reverse mount				SCHA2B0300	3

Dimensions

Standard mount

Unit:mm

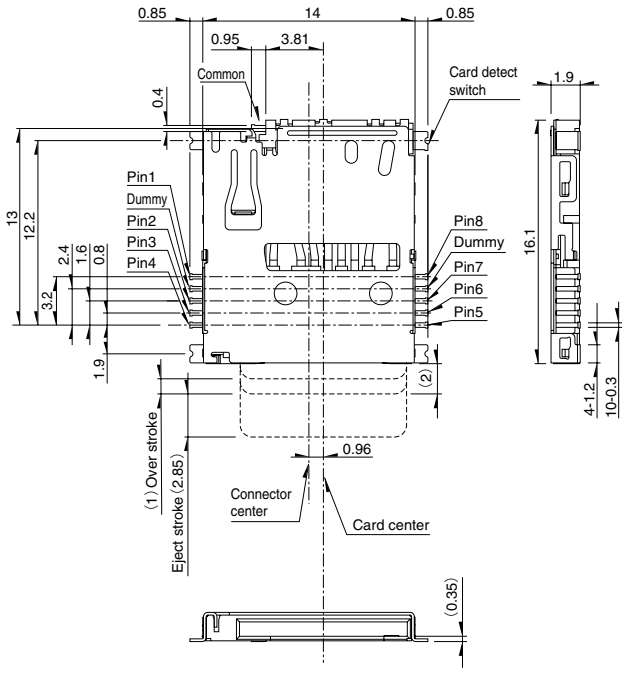
No.	Style	PC board mounting hole dimensions (Viewed from the mounting face side)
1	**Without switch** 	
2	**With switch** 	

Dimensions

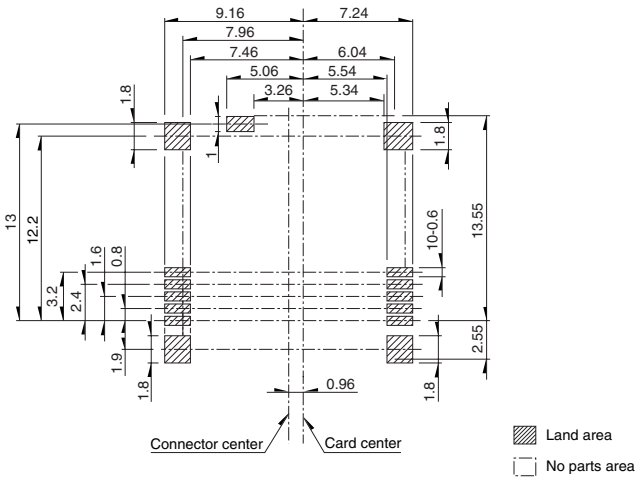
Reverse mount

Unit:mm

No.	Style
3	**With switch**



PC board mounting hole dimensions（Viewed from the mounting face side）

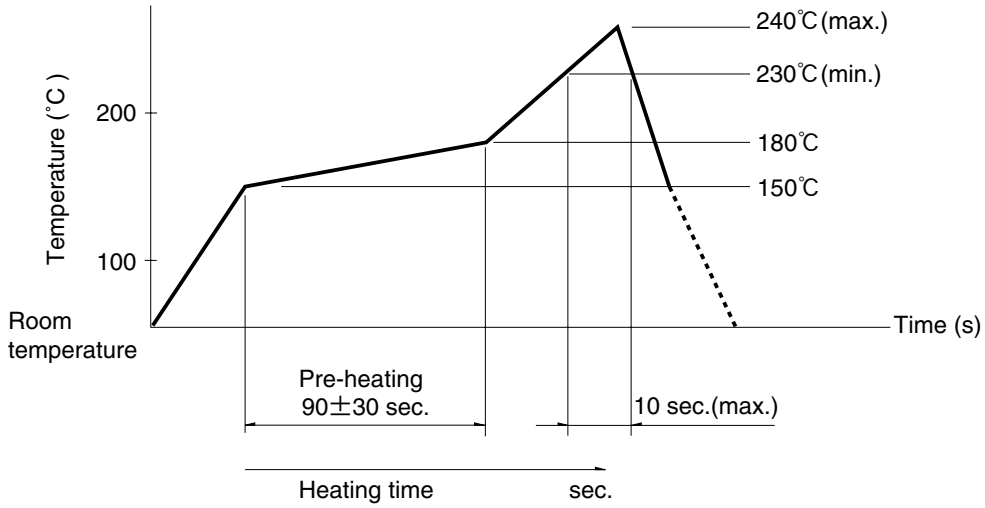


For SD Memory Card
For miniSD™ Card
For microSD™ Card
For RS-MMC™
For W-SIM™
For Memory Stick Micro™
For Memory Stick™
Combine Type
For Compact Flash™
For PC cards supporting CardBus
For Express Card™
For CMOS Camera Module

Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with intrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T).
3. Temperature profile (Surface of products).



Cautions

1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
2. When soldering, do not use water soluble flux because this may corrode the product.
3. Regarding the setting of reflow conditions, please confirm them with the actual mass production conditions.
4. As PC board warping may alter characteristics, please take this into consideration when designing pattern and layout.
5. This product has been designed and manufactured for applications to ordinary electronic equipment and devices such as the AV equipment, electric home applications, office machines and communications equipment, consequently, when employing these products for applications requiring a high degree of safety and reliability such as the medical equipment, aviation and aircraft equipment, space equipment and burglar alarm equipment, the using manufacturers will please thoroughly study the proprieties of these products for the planned applications.
6. The card specifications are provided by the above manufactures. Products by other manufactures may not be compliant with these specifications and are subject to change without prior notice.